

Patent Abstracts of Japan

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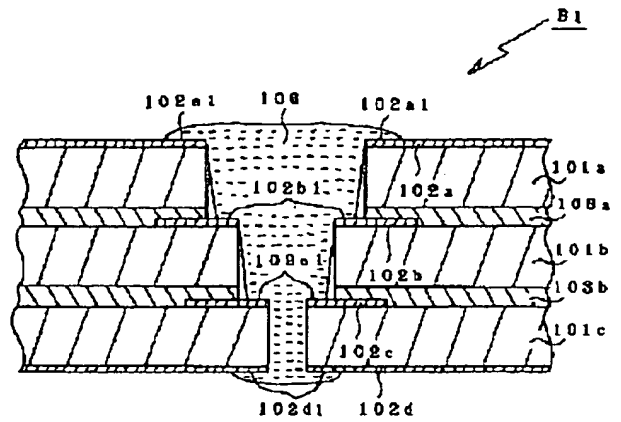
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APPLICANT : NEC HOME ELECTRON LTD;

INVENTOR : UCHIDA HIROSHI;

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TITLE : MULTILAYERED PRINTED WIRING  
BOARD AND ITS MANUFACTURE



ABSTRACT : PURPOSE: To provide a multilayered printed wiring board in which the metallic wiring patterns of the laminated boards constituting the wiring board can be surely electrically connected to each other.

CONSTITUTION: A through hole is formed through a multilayered wiring board B1 manufactured by laminating a plurality of boards 101a-101c carrying metallic wiring patterns 102a-102d on their surfaces upon another by successively and continuously changing the diameter of the through hole from  $\phi a$  to  $\phi c$  at every board 101a-101c and the through hole is filled with conductive paste 106 over the full depth of the through hole from the surface of the board 101a to the bottom of the board 101c.

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